



DATE: 8 April, 2013

PCN #: 2108

PCN Title: Qualification of Additional Wafer Fabrication Sources and
Conversion to Copper Bond Wire on Select Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2108 REV00

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
8 April, 2013	7 July, 2013	Discrete Semiconductors	Additional Wafer Fabrication Source / Bond Wire Material	2108
TITLE				
Qualification of Additional Wafer Fabrication Sources and Conversion to Copper Bond Wire on Select Discrete Products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated is in the process of qualifying additional wafer Fabrication facilities for the devices listed in the Products Affected section of this letter. The alternate wafer manufacturing sites are Sumpro Electronics Corporation (Sumpro), Hua Hong NEC (HHNEC), and/or Maxchip Electronics Corporation (Maxchip).</p> <p>In addition, part numbers marked with an (*) are being converted to Copper bond wire.</p> <p>Full electrical characterization and high reliability testing has either already been completed or will be completed using representative devices built with wafer materials from the additional wafer fabrication sources and/or built using Copper bond wire (as identified above) to ensure there is no change to device functionality or electrical specifications in the datasheet. Diodes will be able to provide qualification data that already exists, or, for ongoing qualifications, as soon as it becomes available.</p> <p>There will be no change to the Form, Fit, or Function of products affected.</p>				
IMPACT				
Continuity of Supply				
PRODUCTS AFFECTED				
Please refer to attached table below				
WEB LINKS				
Manufacturer's Notice:	http://www.diodes.com/quality/pcns			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

PCN-2108 Parts List

DMG7430LFG-7	ZXMN3G32DN8TA	ZXMC3F31DN8TC	DMN6040SSS-13	DMN4030LK3-13*
DMP6180SK3-13	DMG7430LFG-13	ZXMN3G32DN8TC	ZXMHC3F381N8TC	DMN6040SSD-13
DMN6068LK3-13*	DMP10H400SK3-13	DMN3016LFDE-7	DMN3025LFG-13	DMC3028LSD-13
DMN6040SK3-13	DMN6066SSS-13	DMP2008UFG-13	DMN3024LK3-13*	DMN3025LFG-7
DMHC3025LSD-13	DMN6040SFDE-7	DMN2015UFDE-7	DMC4040SSD-13	DMN3024LSD-13
DMP3050LVT-7	DMC6070LFDH-7	DMN10H170SK3-13	DMP4051LK3-13*	DMC4050SSD-13
DMN3024LSS-13	DMP3050LSS-13	DMN6040SVT-7	DMN4034SSD-13	DMP4050SSS-13
ZXMN3F30FHTA	ZXMN3F31DN8TA	DMC3025LSD-13	DMN4060SVT-7	DMN4034SSS-13
DMP4047LFDE-7	ZXMP3F30FHTA	ZXMN3F31DN8TC	ZXMC3F31DN8TA	ZXMN2F30FHTA
ZXMN2F34FHTA	DMN4036LK3-13*	DMN4027SSD-13	DMN6066SSD-13	DMN6068SE-13
DMP4050SSD-13	DMC4028SSD-13			